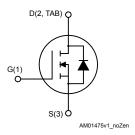


N-channel 60 V, 6.8 mΩ typ., 40 A STripFET™ F7 Power MOSFET in a DPAK package





Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STD80N6F7	60 V	8.0 mΩ	40 A

- Among the lowest R_{DS(on)} on the market
- Excellent FoM (figure of merit)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Product status		
STD80N6F7		
Product summary		
Order code STD80N6F7		
Marking	80N6F7	
Package DPAK		
Packing	Tape and reel	



1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
V _{DS}	Drain-source voltage	60	V	
V _{GS}	Gate-source voltage	±20	V	
I _D ⁽¹⁾	Drain current (continuous) at T _C = 25 °C	40	Α	
I _D ⁽¹⁾	Drain current (continuous) at T _C = 100 °C	40	Α	
I _{DM} ^{(2) (1)}	Drain current (pulsed)	160	Α	
P _{TOT}	Total dissipation at T _C = 25 °C	100	W	
E _{AS} (3)	Single pulse avalanche energy	60	mJ	
dv/dt ⁽⁴⁾	Peak diode recovery	4.3	V/ns	
Tj	Operating junction temperature range	-55 to 175	°C	
T _{stg}	Storage temperature range	-55 to 175		

- 1. This value is limited by package
- 2. Pulse width limited by safe operating area
- 3. Starting $T_j = 25$ °C, $I_{AS} = 20$ A, $V_{DD} = 40$ V.
- 4. I_{SD} = 20 A, di/dt= 700A/ μ s, V_{DD} =48 V.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-pcb} (1)	Thermal resistance junction-pcb	50	°C/W
R _{thj-case}	R _{thj-case} Thermal resistance junction-case		°C/W

1. When mounted on FR-4 board of 1 inch², 2oz Cu, t < 10 s

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2 Electrical characteristics

 T_C = 25 °C unless otherwise specified

Table 3. On/off-state

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	V _{GS} = 0 V, I _D = 1 mA	60			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0 V, V _{DS} = 60 V			1	μΑ
I _{GSS}	Gate-body leakage current	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
V _{GS(th)}	Gate threshold voltage	V _{DD} = V _{GS} , I _D = 250 μA	2		4	V
R _{DS(on)}	Static drain-source on- resistance	V _{GS} = 10 V, I _D = 20 A		6.8	8.0	mΩ

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance		-	1600	-	pF
C _{oss}	Output capacitance	$V_{DS} = 30 \text{ V, f} = 1 \text{ MHz, } V_{GS} = 0 \text{ V}$	-	800	-	pF
C _{rss}	Reverse transfer capacitance		-	50	-	pF
Qg	Total gate charge	V _{DD} = 30 V, I _D = 20 A,	-	25	-	nC
Q _{gs}	Gate-source charge	V _{GS} = 0 to 10 V	-	7.2	-	nC
Q _{gd}	Gate-drain charge	(see Figure 13. Test circuit for gate charge behavior)	-	8	-	nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V_{DD} = 30 V, I_{D} = 20 A, R_{G} = 4.7 Ω , V_{GS} = 10 V (see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	15	-	ns
t _r	Rise time		-	17.6	-	ns
t _{d(off)}	Turn-off delay time		-	24.4	-	ns
t _f	Fall time		-	7.8	-	ns

Table 6. Source-drain diode

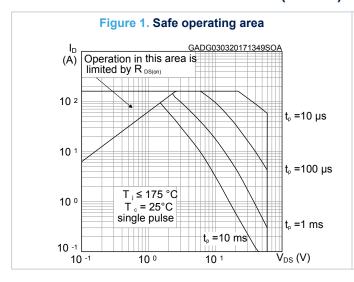
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{SD} ⁽¹⁾	Forward on voltage	I _{SD} = 40 A, V _{DD} = 0 V	-		1.2	V
t _{rr}	Reverse recovery time	I _D = 40 A, di/dt = 100 A/µs ,V _{DD} = 48 V (see Figure 14. Test circuit for inductive load switching and diode recovery times)		39.6		ns
Q _{rr}	Reverse recovery charge			36		nC
I _{RRM}	Reverse recovery current			1.8		Α

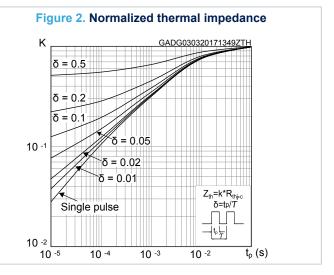
^{1.} Pulsed: pulse duration = 300 μs, duty cycle 1.5%

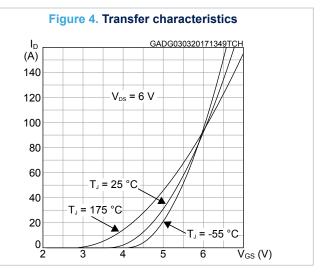
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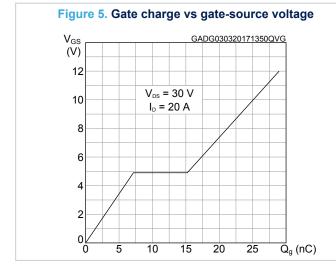


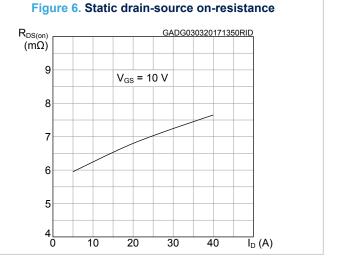
2.1 Electrical characteristics (curves)











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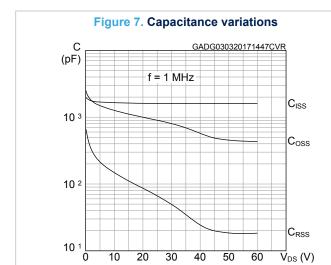
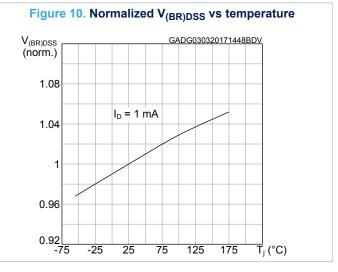
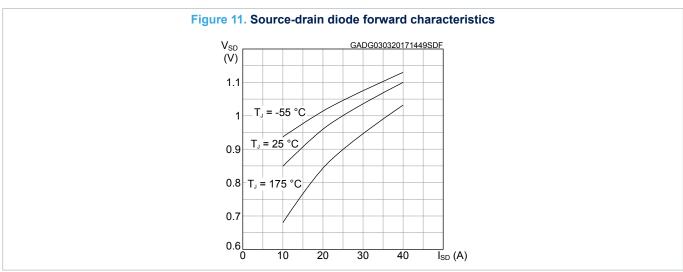


Figure 8. Normalized $V_{GS(th)}$ vs temperature GADG030320171447VTH $V_{\text{GS(th)}}$ (norm.) $I_D = 250 \mu A$ 1.2 1 8.0 0.6 0.2 -75 75 -25 25 125 175 T_j (°C)





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3 Test circuits

Figure 12. Test circuit for resistive load switching times

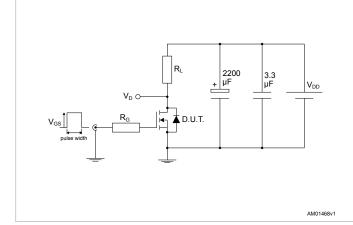


Figure 13. Test circuit for gate charge behavior

Figure 14. Test circuit for inductive load switching and diode recovery times

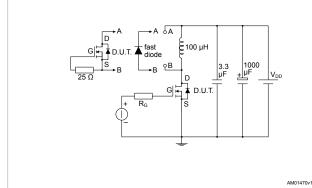


Figure 15. Unclamped inductive load test circuit

AM01471v1

Figure 16. Unclamped inductive waveform

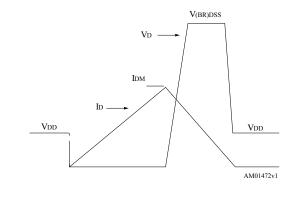
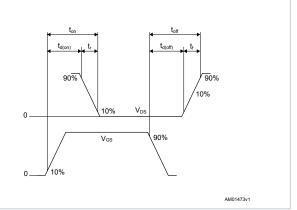


Figure 17. Switching time waveform



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4 Package information

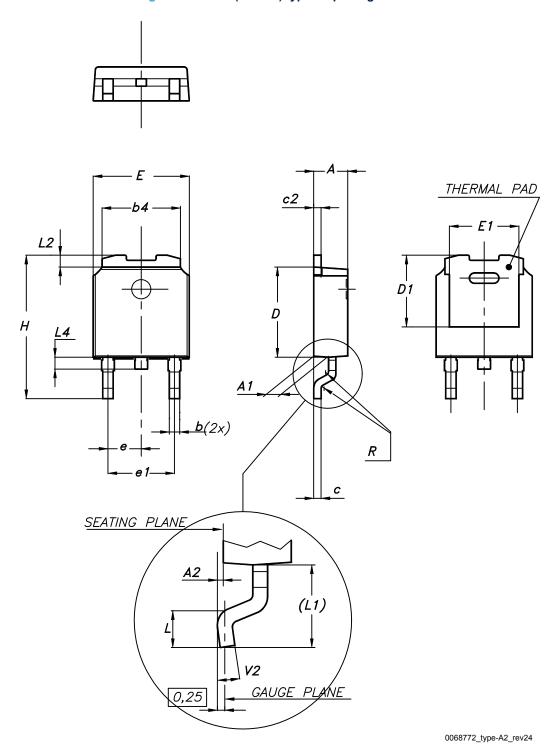
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

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4.1 DPAK (TO-252) type A2 package information

Figure 18. DPAK (TO-252) type A2 package outline



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Table 7. DPAK (TO-252) type A2 mechanical data

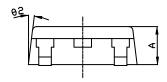
Dim.	mm		
	Min.	Тур.	Max.
Α	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
С	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
е	2.16	2.28	2.40
e1	4.40		4.60
Н	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

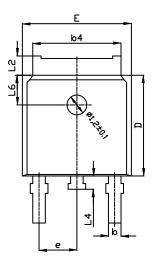
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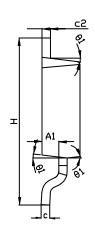


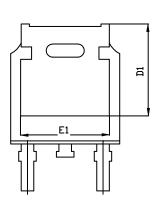
4.2 DPAK (TO-252) type C2 package information

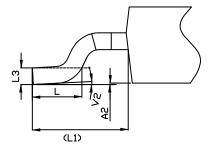
Figure 19. DPAK (TO-252) type C2 package outline











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Table 8. DPAK (TO-252) type C2 mechanical data

Dim.	mm		
	Min.	Тур.	Max.
Α	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46

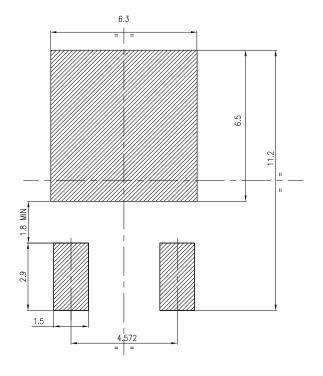
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Dim.	mm		
	Min.	Тур.	Max.
С	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20 5.50		5.50
е	2.186 2.286 2.386		2.386
Н	9.80	10.10	10.40
L	1.40	1.50	1.70
L1		2.90 REF	
L2	0.90		1.25
L3		0.51 BSC	
L4	0.60	0.80	1.00
L6		1.80 BSC	
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

4.3 DPAK (TO-252) footprint information

Figure 20. DPAK (TO-252) recommended footprint (dimensions are in mm)



FP_0068772_24

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Revision history

Table 9. Document revision history

Date	Revision	Changes
03-Nov-2016	1	First release
03-Mar-2017	2	Updated Table 2: "Absolute maximum ratings" and Table 5: "Dynamic".
		Added Section 2.1: "Electrical characteristics (curves)".
		Minor text changes.
02-May-2017	3	Updated Table 2: "Absolute maximum ratings".
01-Feb-2018	4	Added DPAK (TO-252) type C package information.
		Removed maturity status indication from cover page.
12-Feb-2018	5	Modified Section 4 Package information. Minor text changes.

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